

# Beyond glass

## A new reinforcement platform for next-generation electronics

Flexible ceramic nonwoven engineered for RF, high-speed digital, and advanced packaging.

As industry demands grow, new reinforcement alternatives are emerging to support performance, scalability and supply flexibility.

### Why consider Flexiramics?

- Promising results in demanding frequency ranges
- Explore new polymer reinforcement combinations
- Alternative due to glass-fiber supply discussions

### Key advantages

- Lower high-frequency loss
- 4x higher lateral heat spreading
- Drop-in process compatibility
- Thin, stable, and uniform
- Supply chain resilience

### Applications

- RF & mmWave modules
- High-speed digital substrates
- Power electronics
- Advanced packaging



### Samples available:

**Let's build the next generation of laminates together.**